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For Immediate Release

Press Release

Koh Young Technology to Exhibit at SMT Hybrid Packaging 2018

Seoul, South Korea, May 14, 2018 - Under the slogan "True 3D Smart Factory solutions powered by the AI platform," Koh Young Technology will exhibit in Hall 4A, Booth 233, at the upcoming SMT Hybrid Packaging show scheduled to take place June 5-7, 2018 at the Messe in Nuremberg, Germany. The company will display the next-generation premium Zenith2 3D AOI, new 3D Pin inspector KY-P3, and the new automated solder dispensing feature on its 3D SPI.

Latest AOI System

At the show, Koh Young will exhibit Zenith2 3D AOI, which inspects a wide range of mounted components and chips with side-view camera solutions. Zenith2 is the next-generation 3D AOI platform of Zenith series, which recently earned SMT China VISION Award for its innovativeness. This user-friendly, smart 3D AOI was designed according to the latest Industry 4.0 with new features. New features include Auto Programming which automatically sets up inspection conditions, yielding a 70% reduction in programming time, OPO@KSMART (Offline Program Optimizer) to automatically deploy modified inspection conditions without stopping the line.

3D SPI with Auto-Repair

Koh Young will also display enhanced 3D SPI systems with automated solder paste dispensing named Auto-Repair. The high-precision, user-friendly dispensing system helps to eliminate costly mistakes due in large part to insufficient solder in open joints, lean fillets, and weak joints. The KY8030-3 not only inspects solder paste with the highest possible speed and precision, but it repairs insufficient solder defects before pass through, resulting in enhanced first pass yield and reduced operational costs.

New Systems

Leveraging its core strengths in robotics and 3D measurement, Koh Young will also highlight the



new KY-P3 inspection solution. Koh Young's KY-P3 allow check a wide range of pins, including single pin, press-fit, forkpin, pins into chamber (ECU), are correctly aligned with the designated through holes in the circuit board. Thanks to Koh Young's superior 3D imaging technology, it measures the pin height with $\pm 0.75\%$ height accuracy based on Koh Young calibration targets.

As the absolute leader in the SPI and AOI market, Koh Young at Booth 233 in hall 4A, you can learn more about Koh Young Technology and its best-in-class inspection solutions at www.kohyoung.com.

About Koh Young Technology, Inc.

Koh Young Technology Inc., the leading 3D measurement-based inspection equipment and solutions provider, performs an essential role for quality control and process optimization across a growing set of industries including printed circuit board assembly, machining and assembly process manufacturing, semiconductor manufacturing, and various medical fields. In addition to its corporate headquarters in Seoul, Koh Young has sales and support offices in Germany, Japan, Singapore, China, and the United States. These local facilities ensure it maintains close communications with its growing customers base, while providing them with access to a global network of process experts.